Surface Mount Ultrafast Power Rectifiers

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.77 Volts Max @ 2.0 A, T_J = 150°C)
- NRVUS and SURS8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm Tape and Reel, 2500 units per reel
- Polarity: Polarity Band Indicates Cathode Lead
- Marking: U2D
- ESD Ratings:
 - Machine Model = C > 400 V
 - Human Body Model = 3B (> 8 kV)



ON Semiconductor®

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ULTRAFAST RECTIFIERS 2 AMPERES 200 VOLTS



SMB CASE 403A

MARKING DIAGRAM



U2D = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] | |
|--------------|------------------|------------------------|--|
| MURS220T3G | SMB (Pb-Free) | 2,500 / Tape & Reel | |
| NRVUS220VT3G | SMB (Pb-Free) | 2,500 / Tape & Reel | |
| SURS8220T3G | SMB (Pb-Free) | 2,500 / Tape & Reel | |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|--|------------------------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 200 | V |
| Average Rectified Forward Current | I _{F(AV)} | 2.0 @ T _L = 145°C | Α |
| Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz) | I _{FSM} | 40 | А |
| Operating Junction Temperature Range | TJ | -65 to +175 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

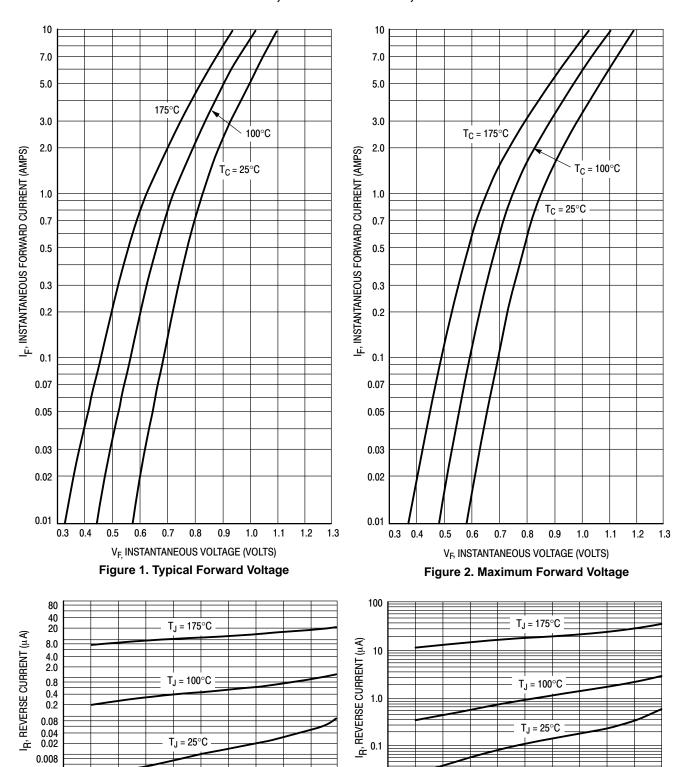
| Characteristic | Symbol | Value | Unit |
|--|---------------|-------|------|
| Thermal Resistance, Junction to Lead (T _L = 25°C) | $R_{	hetaJL}$ | 13 | °C/W |

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|--------------|-------|
| Maximum Instantaneous Forward Voltage (Note 1) $(I_F = 2.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(I_F = 2.0 \text{ A}, T_J = 150^{\circ}\text{C})$ | VF | 0.95 0.77 | Volts |
| Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T _J = 25°C) (Rated dc Voltage, T _J = 150°C) | I _R | 2.0 50 | μА |
| Maximum Reverse Recovery Time $ (I_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) $ $ (I_F = 0.5 \text{ A, } I_R = 1.0 \text{ A, } I_R \text{ to } 0.25 \text{ A}) $ | t _{rr} | 35 25 | ns |
| Maximum Forward Recovery Time ($I_F = 1.0 \text{ A}$, di/dt = 100 A/ μ s, Rec. to 1.0 V) | t _{fr} | 25 | ns |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



V_R, REVERSE VOLTAGE (VOLTS) Figure 3. Typical Reverse Current*

120

160

180 200

 $T_J = 25^{\circ}C$

0.008 0.004 0.002

20

* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied V_B is sufficiently below rated V_R.

V_R, REVERSE VOLTAGE (VOLTS) Figure 4. Maximum Reverse Current

100 120 140

160

180

80

0.01

0 20 40

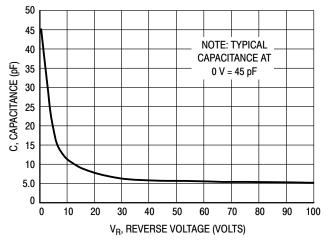


Figure 5. Typical Capacitance

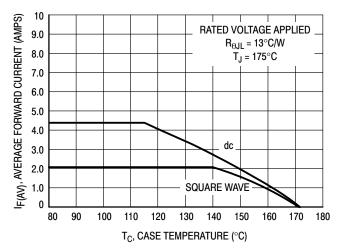


Figure 6. Current Derating, Case

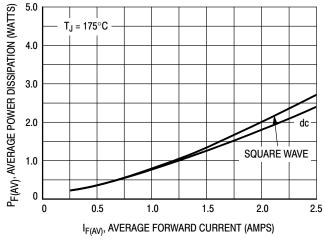
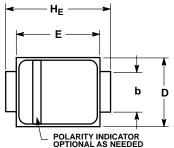
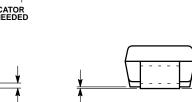


Figure 7. Power Dissipation

PACKAGE DIMENSIONS

SMB CASE 403A-03 ISSUE J



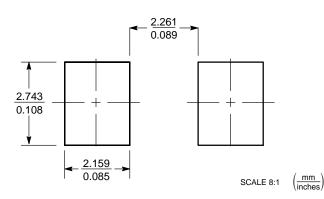


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|-----------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 1.95 | 2.30 | 2.47 | 0.077 | 0.091 | 0.097 |
| A1 | 0.05 | 0.10 | 0.20 | 0.002 | 0.004 | 0.008 |
| b | 1.96 | 2.03 | 2.20 | 0.077 | 0.080 | 0.087 |
| С | 0.15 | 0.23 | 0.31 | 0.006 | 0.009 | 0.012 |
| D | 3.30 | 3.56 | 3.95 | 0.130 | 0.140 | 0.156 |
| E | 4.06 | 4.32 | 4.60 | 0.160 | 0.170 | 0.181 |
| HE | 5.21 | 5.44 | 5.60 | 0.205 | 0.214 | 0.220 |
| L | 0.76 | 1.02 | 1.60 | 0.030 | 0.040 | 0.063 |
| L1 | 0.51 REF | | 0.020 REF | | | |

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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